PRODUCTS AFFECTED:

| SP385ECA-L | SP385ECA-L/ TR | SP385EEA-L | SP385EEA-L/ TR |
| SP211CA-L | SP211CA-L/ TR | SP211EA-L | SP211EA-L/ TR |
| SP211ECA-L | SP211ECA-L/ TR | SP211EEA-L | SP211EEA-L/ TR |
| SP211EHCA-L | SP211EHCA-L/ TR | SP211EHEA-L | SP211EHEA-L/ TR |
| SP213ECA-L | SP213ECA-L/ TR | SP213EEA-L | SP213EEA-L/ TR |
| SP213EHCA-L | SP213EHCA-L/ TR | SP213EHEA-L | SP213EHEA-L/ TR |

CHANGE CATEGORY:

- Material
- Process
- Package
- Design
- Datasheet
- Packing/Shipping
- Other (specify)

DESCRIPTION OF CHANGE:
Qualified copper wire bonding assembly in addition to currently qualified gold wire bonding assembly in Carsem.

IMPACT OF CHANGE:
There will be no change to product form, fit or function.

TARGET IMPLEMENTATION DATE: 21-Aug-2013

Please contact customer support (customersupport@exar.com) for sample date availability or qualification data.